

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1764AEFE-3.3#TRPBF		(Engineering Calculation)		TSSOP Exp. Pad				
(printed on: 7/16/2011 12:51:10 PM)				TOTAL MASS (g):		0.07066491		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005437	1000000	76940.59		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.025576	975000	361933.5		
		Iron (Fe)	7439-89-6	0.00063	24000	8915.316		
		Phosphorus (P)	7723-14-0	8.00E-06	300	113.2104		
		Zinc (Zn)	7440-66-6	1.80E-05	700	254.7233		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.026232	1000000	371216.8
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.00236391	1000000	33452.38		
		External Plating Total:				0.00236391	1000000	33452.38
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	0.00103	1000000	14575.83		
		Internal Plating Total:				0.00103	1000000	14575.83
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001372	750000	19415.58		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0.000457	250000	6467.142		
Die Attach Total:				0.001829	1000000	25882.72		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004875	150000	68987.56		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.02665	820000	377132		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0.000813	25000	11505		
		Carbon Black (C)	1333-86-4	0.000163	5000	2306.661		
Encapsulation Total:				0.032501	1000000	459931.3		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001272	1000000	18000.45		
Estimated								
TOTAL MASS (g):						0.07066491		